Initial Product/Process Change Notification
Document #:IPCN22966ZD1
Issue Date: 19 Jul 2022

Title of Change:	Update to IPCN22966ZD – Removal of NVMFS5C460NWFT1G device from the IPCN22966ZD scope.
Proposed Changed Material First Ship Date:	N/A
Current Material Last Order Date:	N/A
Current Material Last Delivery Date:	N/A
Product Category:	Active components – Discrete components
Contact information:	Contact your local onsemi Sales Office or Ammar.Anuar@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Robert.Baran@onsemi.com
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.

Change Category

Category	**Type of Change**
Packing/Shipping	Dry pack requirements change
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor Change of gate material / dielectrics, New wafer diameter
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change in process technology (e.g., die attach, bonding, moulding, plating, trim and form, lead frame preperation, …), Change in leadframe dimensions

Description and Purpose:

This Product Change Notification Update is intended to inform the customers that the device NVMFS5C460NWFT1G is being removed from the IPCN22966ZD scope.

IPCN22966ZD previously announced the Wafer Fab Transfer for Trench 6 MOSFET Technology to Global Foundries in New York, US.

Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Seremban, Malaysia	Global Foundries East Fishkill, New York, United States
	Metek Seremban, Malaysia

Marking of Parts/ Traceability of Change:	Material will be traceable with ONs lot trace code & tracking

Reliability Data Summary:

Not applicable.

Electrical Characteristics Summary:

Not applicable.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Current Part Number	New Part Number	Qualification Vehicle
NVMFS5C460NWFT1G	N/A	N/A